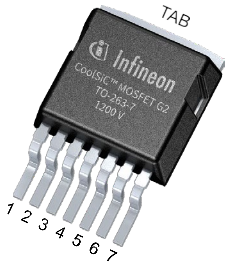
最终数据表

英飞凌CoolSiC ™ 1200 V SiC MOSFET G2：碳化硅 MOSFET



Halogen-free
Green
Lead-free
RoHS

特性

- T_{vj} = 25°C 时 V_{DSS} = 1200 V
- T_C = 100°C 时 I_{DDC} = 43 A
- $R_{DS(on)}$ = 34 mΩ （V_{GS} = 18V、Tvj = 25°C 时）
- 开关损耗非常低
- 过载运行最高结温可达 T_{vj} = 200°C
- 短路耐受时间 2 µs
- 基准栅极阈值电压，$V_{GS(th)}$ = 4.2 V
- 具有抗寄生导通能力，可应用 0 V 关断栅极电压
- 坚固的体二极管，适用于硬换向
- 英飞凌.XT 互连技术，实现业界领先的热性能
- 合适的英飞凌栅极驱动器可在 https://www.infineon.com/gdfinder 找到

潜在的应用

- 电动汽车充电桩
- 在线式UPS/工业UPS
- 组串式逆变器
- 通用驱动器 (GPD)

产品认证

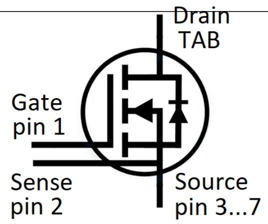
- 符合JEDEC47/20/22相关测试的工业应用要求

描述

引脚定义：

- 引脚 1 - 栅极
- 引脚 2 - 开尔文感应
- 引脚 3...7 - 源极
- Tab - 漏极

注意：源极和开尔文传感触点引脚不可互换，互换可能会导致故障（仅适用于 4 pin及TO263-7L封装）



Type	Package	Marking
IMBG120R034M2H	PG-TO263-7-U01	12M2H034

目录

1 封装

表1 特征值

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Storage temperature	T_{stg}		-55		150	°C
Soldering temperature	T_{sold}	reflow soldering (MSL1 according to JEDEC J-STD-020)			260	°C
Thermal resistance, junction-ambient	$R_{th(j-a)}$				62	K/W
MOSFET/body diode thermal resistance, junction-case	$R_{th(j-c)}$			0.41	0.53	K/W

2 MOSFET

表2 最大额定值

Parameter	Symbol	Note or test condition		Values	Unit
Drain-source voltage	V_{DSS}	$T_{vj} \geq 25$ °C		1200	V
Continuous DC drain current for $R_{th(j-c,max)}$, limited by $T_{vj(max)}$	I_{DDC}	$V_{GS} = 18$ V	$T_c = 25$ °C	58	A
			$T_c = 100$ °C	42	
Peak drain current, t_p limited by $T_{vj(max)}$ 1)	I_{DM}	$V_{GS} = 18$ V		126	A
Gate-source voltage, max. transient voltage	V_{GS}	$t_p \leq 0.5$ µs, $D < 0.01$		-10...25	V
Gate-source voltage, max. static voltage 2)	V_{GS}			-7...23	V
Avalanche energy, single pulse	E_{AS}	$I_D = 20.4$ A, $V_{DD} = 50$ V, $L = 1.2$ mH		256	mJ
Avalanche energy, repetitive	E_{AR}	$I_D = 20.4$ A, $V_{DD} = 50$ V, $L = 6.2$ µH		1.39	mJ
Short-circuit withstand time	t_{SC}	$V_{DD} \leq 800$ V, $V_{DS,peak} < 1200$ V, $V_{GS(on)} = 15$ V, $T_{vj(start)} = 25$ °C		2	µs
Power dissipation, limited by $T_{vj(max)}$	P_{tot}		$T_c = 25$ °C	278	W
			$T_c = 100$ °C	139	

1) 已通过设计验证。
2) 应用设计中的最大栅源电压应符合IPC-9592B的规定。

表 3 建议值

Parameter	Symbol	Note or test condition	Values	Unit
Recommended turn-on gate voltage	$V_{GS(on)}$		15...18	V
Recommended turn-off gate voltage	$V_{GS(off)}$		-5...0	V

表4 特征值

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Drain-source on-state resistance	$R_{DS(on)}$	I_D = 20.4 A	T_{vj} = 25 °C, $V_{GS(on)}$ = 18 V		34		mΩ
			T_{vj} = 150 °C, $V_{GS(on)}$ = 18 V		69.3	90	
			T_{vj} = 175 °C, $V_{GS(on)}$ = 18 V		80.4		
			T_{vj} = 25 °C, $V_{GS(on)}$ = 15 V		42.4		
Gate-source threshold voltage	$V_{GS(th)}$	I_D = 6.4 mA, V_{DS} = V_{GS} (tested after 1 ms pulse at V_{GS} = 20 V)	T_{vj} = 25 °C	3.5	4.2	5.1	V
			T_{vj} = 175 °C		3.2		
Zero gate-voltage drain current	I_{DSS}	V_{DS} = 1200 V, V_{GS} = 0 V	T_{vj} = 25 °C			180	µA
			T_{vj} = 175 °C		3		
Gate leakage current	I_{GSS}	V_{DS} = 0 V	V_{GS} = 23 V			120	nA
			V_{GS} = -10 V			-120	
Forward transconductance	g_{fs}	I_D = 20.4 A, V_{DS} = 20 V			13.7		S
Internal gate resistance	$R_{G,int}$	f = 1 MHz, V_{AC} = 25 mV			6.1		Ω
Input capacitance	C_{iss}	V_{DD} = 800 V, V_{GS} = 0 V, f = 100 kHz, V_{AC} = 25 mV			1510		pF
Output capacitance	C_{oss}	V_{DD} = 800 V, V_{GS} = 0 V, f = 100 kHz, V_{AC} = 25 mV			64		pF
Reverse transfer capacitance	C_{rss}	V_{DD} = 800 V, V_{GS} = 0 V, f = 100 kHz, V_{AC} = 25 mV			5.8		pF
C_{oss} stored energy	E_{oss}	V_{DD} = 800 V, V_{GS} = 0 V, f = 100 kHz, V_{AC} = 25 mV			27		µJ
Output charge	Q_{oss}	V_{GS} = 0 V, Calculated by $C_{oss}(f)V_{DS}$ @100 kHz			98.8		nC
Effective output capacitance, energy related	$C_{o(er)}$	V_{DD} = 0...800 V, V_{GS} = 0 V			84.4		pF
Effective output capacitance, time related	$C_{o(tr)}$	I_D = constant, V_{DD} = 0...800 V, V_{GS} = 0 V			123.5		pF
Total gate charge	Q_G	V_{DD} = 800 V, I_D = 20.4 A, V_{GS} = -2/18 V, turn-on pulse			45		nC

（表格续下页……）

表 4 （续） 特征值

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Plateau gate charge	$Q_{GS(pl)}$	V_{DD} = 800 V, I_D = 20.4 A, V_{GS} = -2/18 V, turn-on pulse			9.8		nC
Gate-to-drain charge	Q_{GD}	V_{DD} = 800 V, I_D = 20.4 A, V_{GS} = -2/18 V, turn-on pulse			12.1		nC
Turn-on delay time	$t_{d(on)}$	V_{DD} = 800 V, I_D = 20.4 A, V_{GS} = 0/18 V, $R_{GS(on)}$ = 2.3 Ω, $R_{GS(off)}$ = 2.3 Ω, L_σ = 15 nH, diode: body diode at V_{GS} = 0 V	T_{vj} = 25 °C		4		ns
			T_{vj} = 175 °C		4.1		
Rise time	t_r	V_{DD} = 800 V, I_D = 20.4 A, V_{GS} = 0/18 V, $R_{GS(on)}$ = 2.3 Ω, $R_{GS(off)}$ = 2.3 Ω, L_σ = 15 nH, diode: body diode at V_{GS} = 0 V	T_{vj} = 25 °C		15.5		ns
			T_{vj} = 175 °C		15.2		
Turn-off delay time	$t_{d(off)}$	V_{DD} = 800 V, I_D = 20.4 A, V_{GS} = 0/18 V, $R_{GS(on)}$ = 2.3 Ω, $R_{GS(off)}$ = 2.3 Ω, L_σ = 15 nH, diode: body diode at V_{GS} = 0 V	T_{vj} = 25 °C		8.1		ns
			T_{vj} = 175 °C		14		
Fall time	t_f	V_{DD} = 800 V, I_D = 20.4 A, V_{GS} = 0/18 V, $R_{GS(on)}$ = 2.3 Ω, $R_{GS(off)}$ = 2.3 Ω, L_σ = 15 nH, diode: body diode at V_{GS} = 0 V	T_{vj} = 25 °C		5.2		ns
			T_{vj} = 175 °C		6.1		
Turn-on energy	E_{on}	V_{DD} = 800 V, I_D = 20.4 A, V_{GS} = 0/18 V, $R_{GS(on)}$ = 2.3 Ω, $R_{GS(off)}$ = 2.3 Ω, L_σ = 15 nH, diode: body diode at V_{GS} = 0 V	T_{vj} = 25 °C		140		µJ
			T_{vj} = 175 °C		272		
Turn-off energy	E_{off}	V_{DD} = 800 V, I_D = 20.4 A, V_{GS} = 0/18 V, $R_{GS(on)}$ = 2.3 Ω, $R_{GS(off)}$ = 2.3 Ω, L_σ = 15 nH, diode: body diode at V_{GS} = 0 V	T_{vj} = 25 °C		27		µJ
			T_{vj} = 175 °C		41		

（表格续下页......）

表 4　　　（续） 特征值

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Total switching energy[1]	E_{tot}	V_{DD} = 800 V, I_D = 20.4 A, V_{GS} = 0/18 V, $R_{GS(on)}$ = 2.3 Ω, $R_{GS(off)}$ = 2.3 Ω, L_σ = 15 nH, diode: body diode at V_{GS} = 0 V	T_{vj} = 25 °C		217		µJ
			T_{vj} = 175 °C		463		
Virtual junction temperature	T_{vj}			-55		175	°C
Virtual junction temperature	$T_{vj(over)}$	overload, cumulative max. 100 h[2]				200	°C

1) 包括 E_{fr}
2) 最多 5000 次循环。最大Δ T 限制为 100 K。

注：芯片技术的特征是高达200 kV/µs。测量的dV/dt 受到测量测试设置和封装的限制。

除非另有规定，*特性均为 T_{vj} = 25°C。*

3　体二极管（MOSFET）

表5　　最大额定值

Parameter	Symbol	Note or test condition	Values	Unit
Drain-source voltage	V_{DSS}	T_{vj} ≥ 25 °C	1200	V
Peak reverse drain current, t_p limited by $T_{vj(max)}$	I_{SM}	V_{GS} = 0 V	52	A

表6　　特征值

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Drain-source reverse voltage	V_{SD}	I_{SD} = 20.4 A, V_{GS} = 0 V	T_{vj} = 25 °C		4.2	5.5	V
			T_{vj} = 100 °C		4.11		
			T_{vj} = 175 °C		4.05		
MOSFET forward recovery charge	Q_{fr}	V_{DD} = 800 V, I_{SD} = 20.4 A, V_{GS} = 0 V, $-di_{SD}/dt$ = 1000 A/µs, Q_{fr} includes also Q_C	T_{vj} = 25 °C		0.23		µC
			T_{vj} = 175 °C		0.41		
MOSFET peak forward recovery current	I_{frm}	V_{DD} = 800 V, I_{SD} = 20.4 A, V_{GS} = 0 V, $-di_{SD}/dt$ = 1000 A/µs, Q_{fr} includes also Q_C	T_{vj} = 25 °C		7.3		A
			T_{vj} = 175 °C		9.8		

（表格续下页……）

表 6（续）特征值

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
MOSFET forward recovery energy	E_{fr}	V_{DD} = 800 V, I_{SD} = 20.4 A, V_{GS} = 0 V, $-di_{SD}/dt$ = 1000 A/µs, Q_{fr} includes also Q_C	T_{vj} = 25 °C		50		µJ
			T_{vj} = 175 °C		150		
Virtual junction temperature	T_{vj}			-55		175	°C
Virtual junction temperature	$T_{vj(over)}$	overload, cumulative max. 100 h[1)]				200	°C

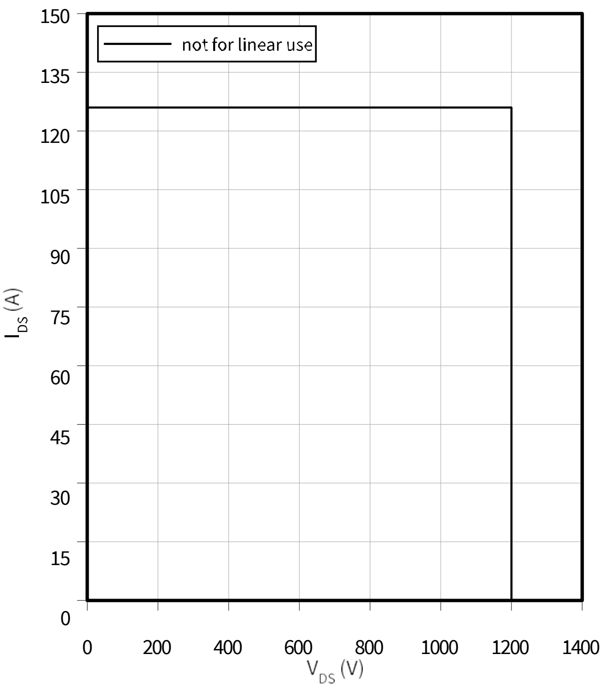
1) 最多 5000 次循环。最大Δ T 限制为 100 K。

4 特性图

Reverse bias safe operating area (RBSOA)

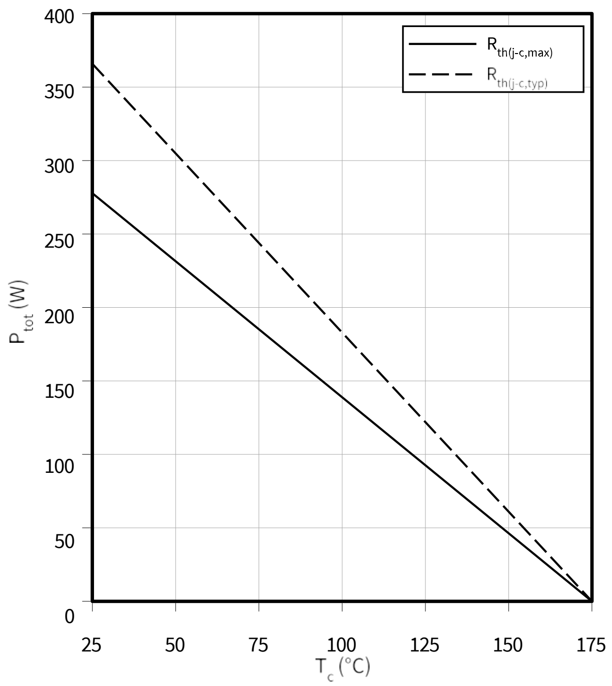
$I_{DS} = f(V_{DS})$

$T_{vj} \leq 175\ °C$, $V_{GS} = 0/18\ V$, $T_c = 25\ °C$



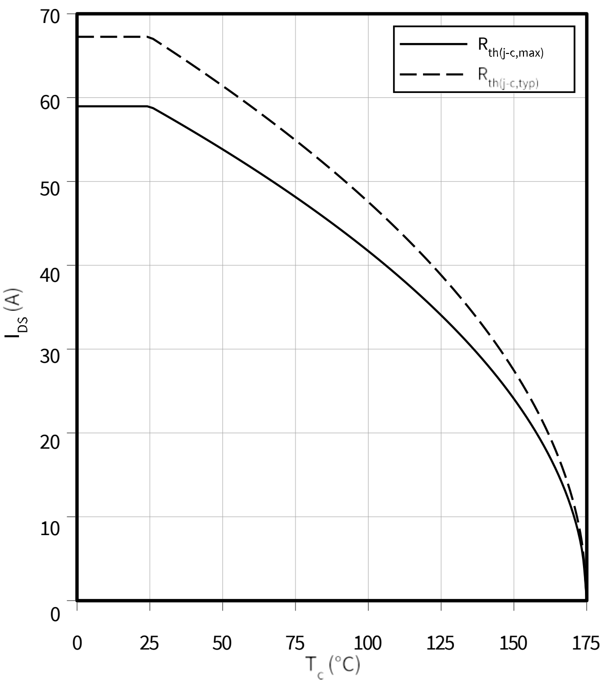
Power dissipation as a function of case temperature limited by bond wire

$P_{tot} = f(T_c)$



Maximum DC drain to source current as a function of case temperature limited by bond wire

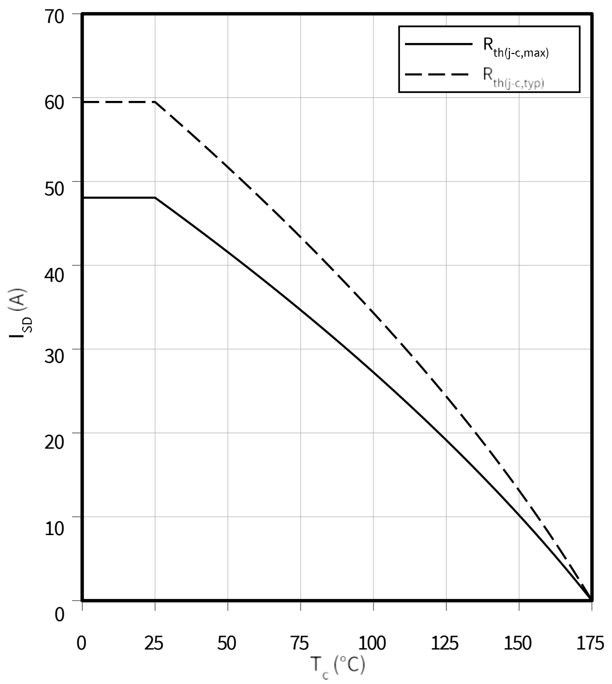
$I_{DS} = f(T_c)$

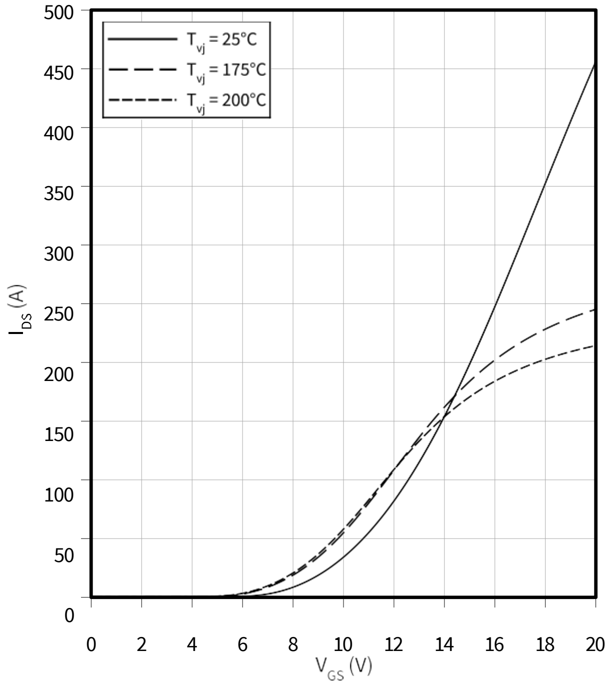
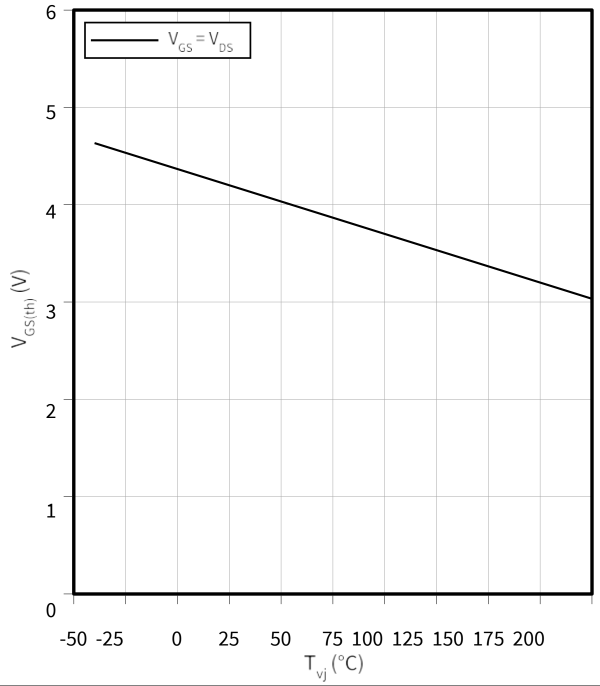
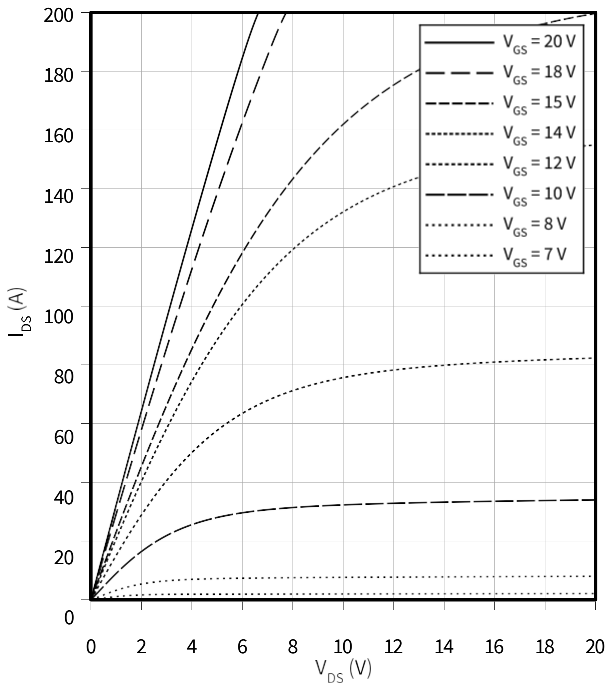
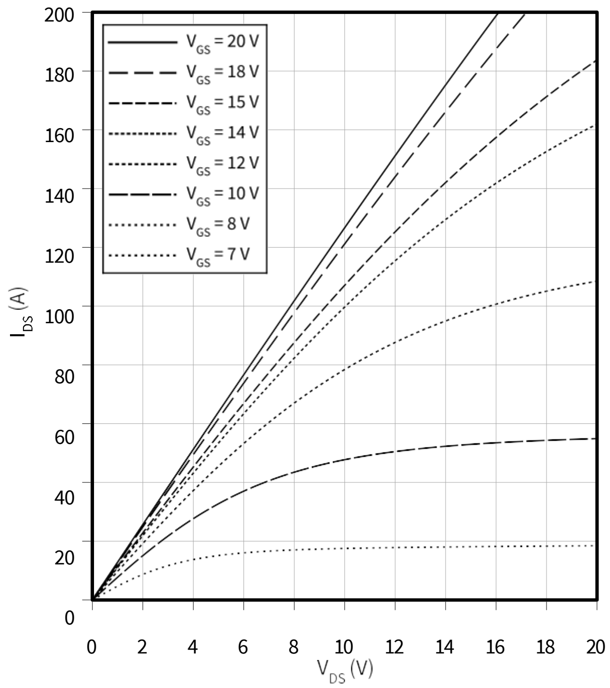


Maximum source to drain current as a function of case temperature limited by bond wire

$I_{SD} = f(T_c)$

$V_{GS} = 0\ V$

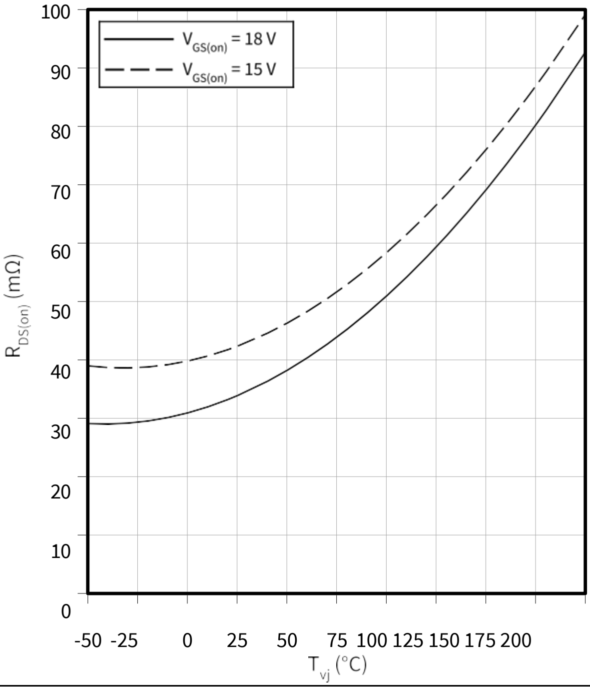


Typical transfer characteristic $I_{DS} = f(V_{GS})$ $V_{DS} = 20$ V, $t_p = 20$ µs	**Typical gate-source threshold voltage as a function of junction temperature** $V_{GS(th)} = f(T_{vj})$ $I_D = 6.4$ mA
	
Typical output characteristic, V_{GS} as parameter $I_{DS} = f(V_{DS})$ $T_{vj} = 25$ °C, $t_p = 20$ µs	**Typical output characteristic, V_{GS} as parameter** $I_{DS} = f(V_{DS})$ $T_{vj} = 175$ °C, $t_p = 20$ µs
	

Typical on-state resistance as a function of junction temperature

$R_{DS(on)} = f(T_{vj})$

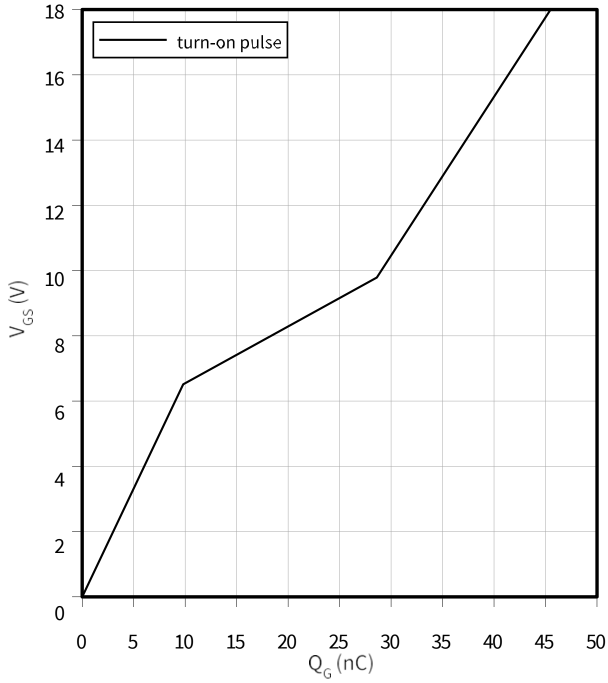
$I_D = 20.4$ A



Typical gate charge

$V_{GS} = f(Q_G)$

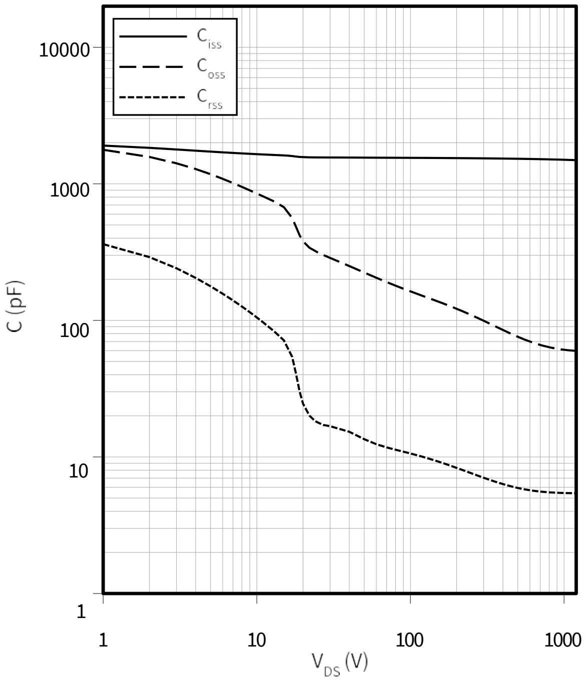
$I_D = 20.4$ A, $V_{DS} = 800$ V



Typical capacitance as a function of drain-source voltage

$C = f(V_{DS})$

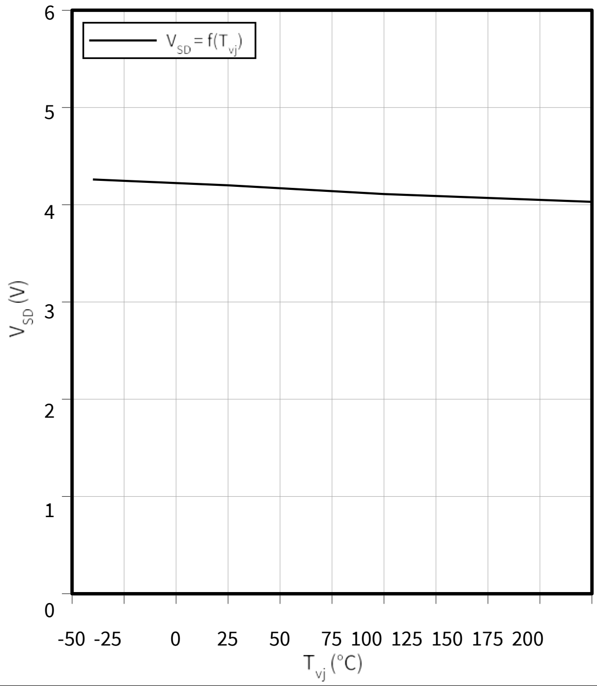
$f = 100$ kHz, $V_{GS} = 0$ V



Typical reverse drain voltage as function of junction temperature

$V_{SD} = f(T_{vj})$

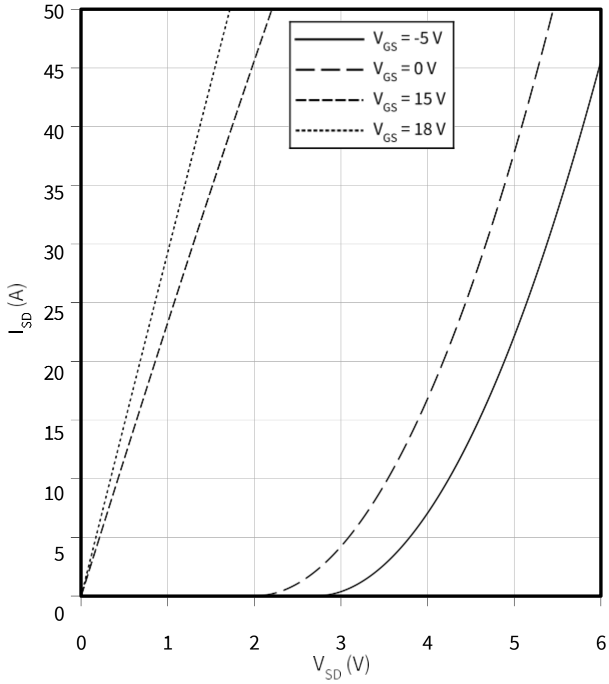
$I_{SD} = 20.4$ A, $V_{GS} = 0$ V



Typical reverse drain current as function of reverse drain voltage, V_{GS} as parameter

$I_{SD} = f(V_{SD})$

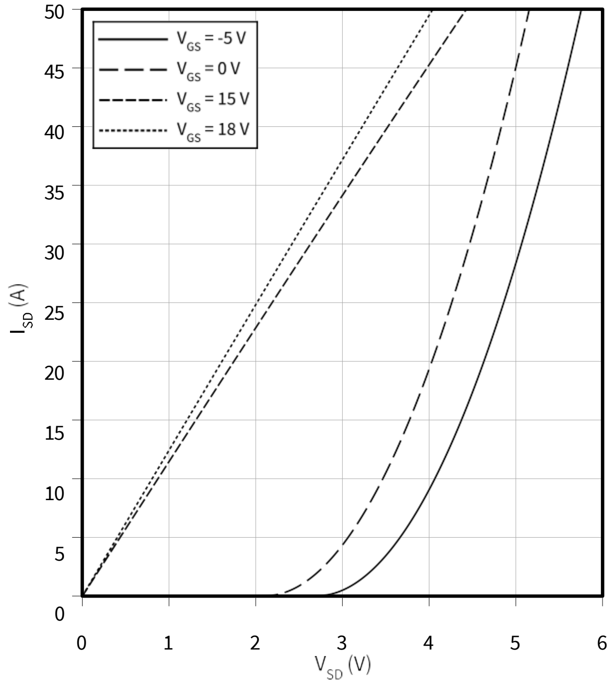
$T_{vj} = 25$ °C, $t_p = 20$ µs



Typical reverse drain current as function of reverse drain voltage, V_{GS} as parameter

$I_{SD} = f(V_{SD})$

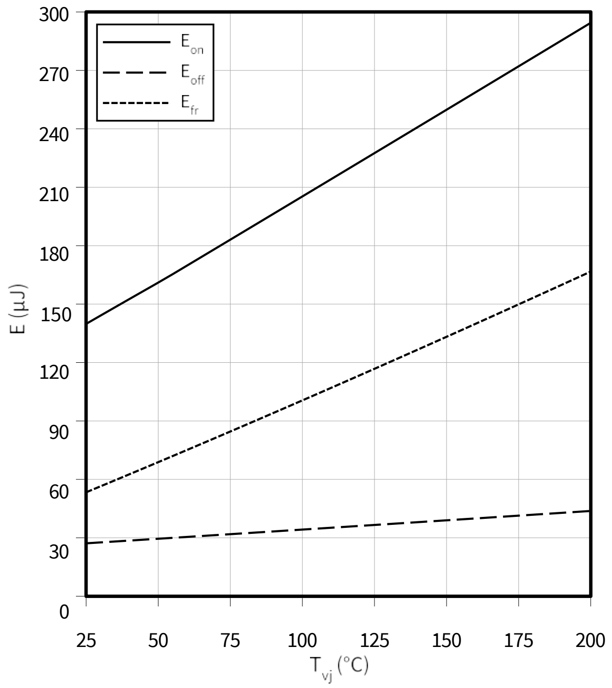
$T_{vj} = 175$ °C, $t_p = 20$ µs



Typical switching energy as a function of junction temperature, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0$ V

$E = f(T_{vj})$

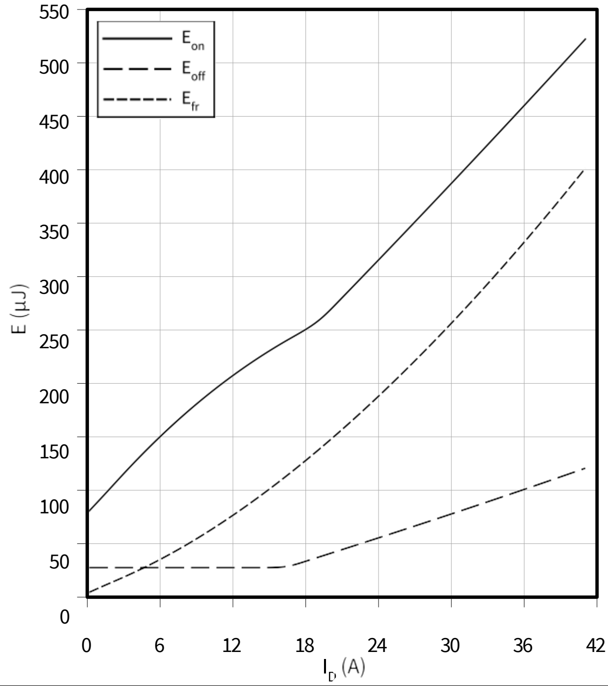
$V_{GS} = 0/18$ V, $I_D = 20.4$ A, $R_{G,ext} = 2.3\ \Omega$, $V_{DD} = 800$ V



Typical switching energy as a function of drain current, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0$ V

$E = f(I_D)$

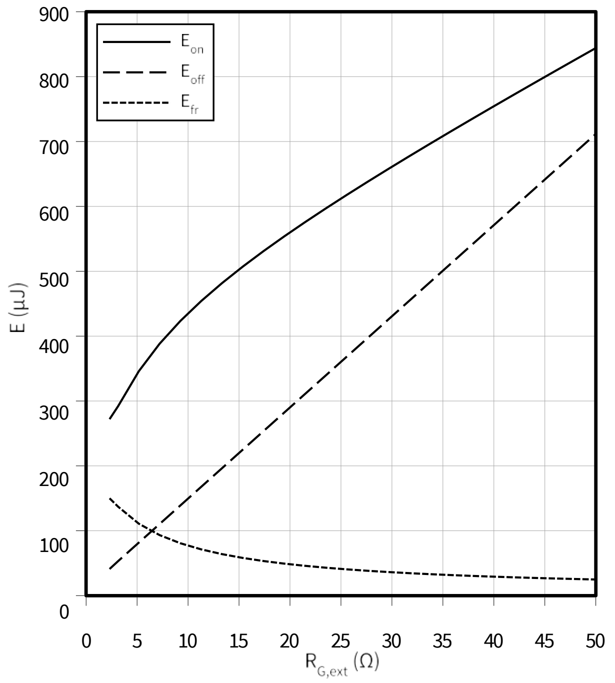
$V_{GS} = 0/18$ V, $T_{vj} = 175$ °C, $R_{G,ext} = 2.3\ \Omega$, $V_{DD} = 800$ V



Typical switching energy as a function of gate resistance, test circuit in Fig. F, 2nd device own body diode: V_{GS} = 0 V

$E = f(R_{G,ext})$

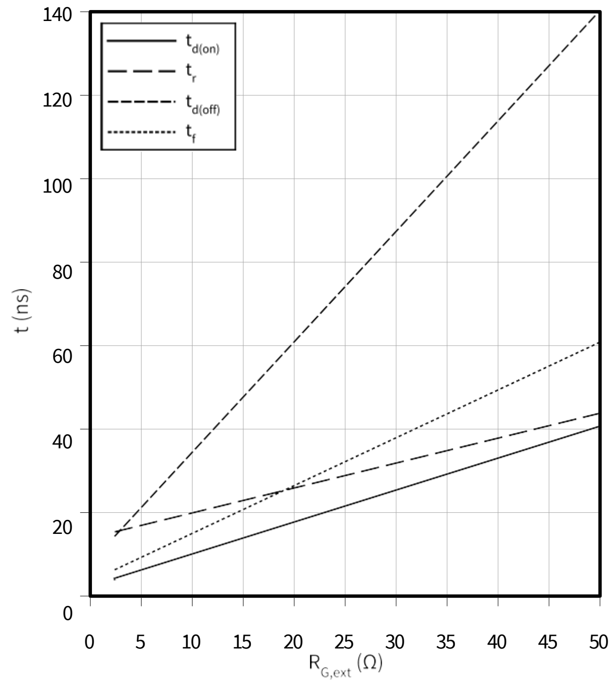
V_{GS} = 0/18 V, I_D = 20.4 A, T_{vj} = 175 °C, V_{DD} = 800 V



Typical switching times as a function of gate resistance, test circuit in Fig. F, 2nd device own body diode: V_{GS} = 0 V

$t = f(R_{G,ext})$

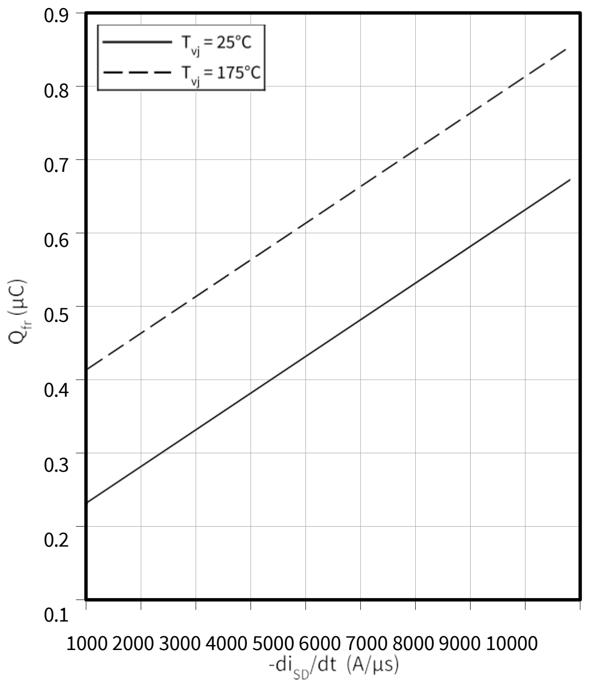
V_{GS} = 0/18 V, I_D = 20.4 A, T_{vj} = 175 °C, V_{DD} = 800 V



Typical reverse recovery charge as a function of reverse drain current slope, test circuit in Fig. F, 2nd device own body diode: V_{GS} = 0 V

$Q_{fr} = f(-di_{SD}/dt)$

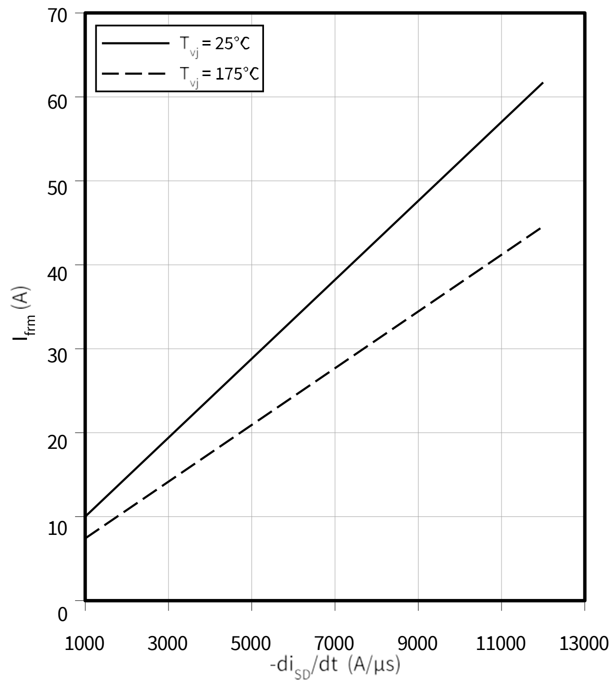
V_{GS} = 0/18 V, I_{SD} = 20.4 A, V_{DD} = 800 V

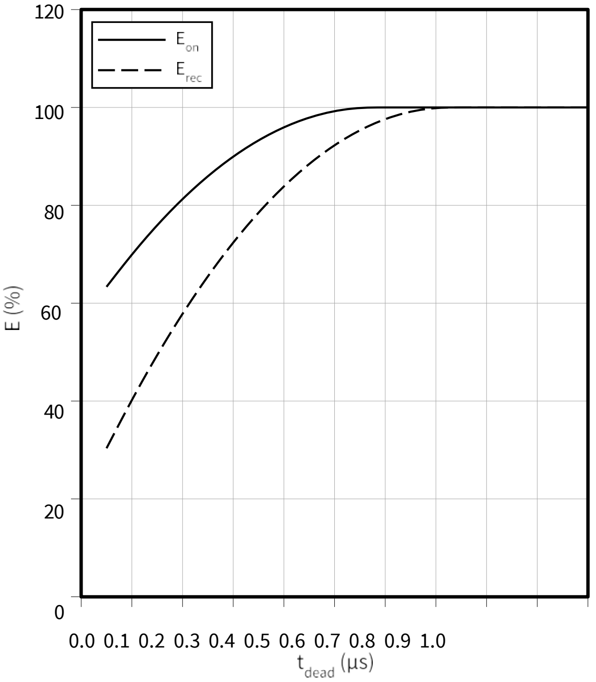
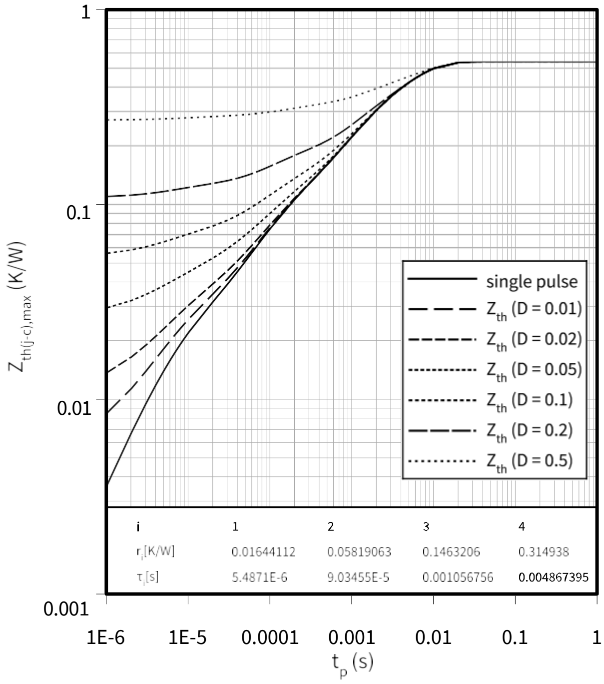


Typical MOSFET peak forward recovery current as a function of reverse drain current slope, test circuit in Fig. F, 2nd device own body diode: V_{GS} = 0 V

$I_{frm} = f(-di_{SD}/dt)$

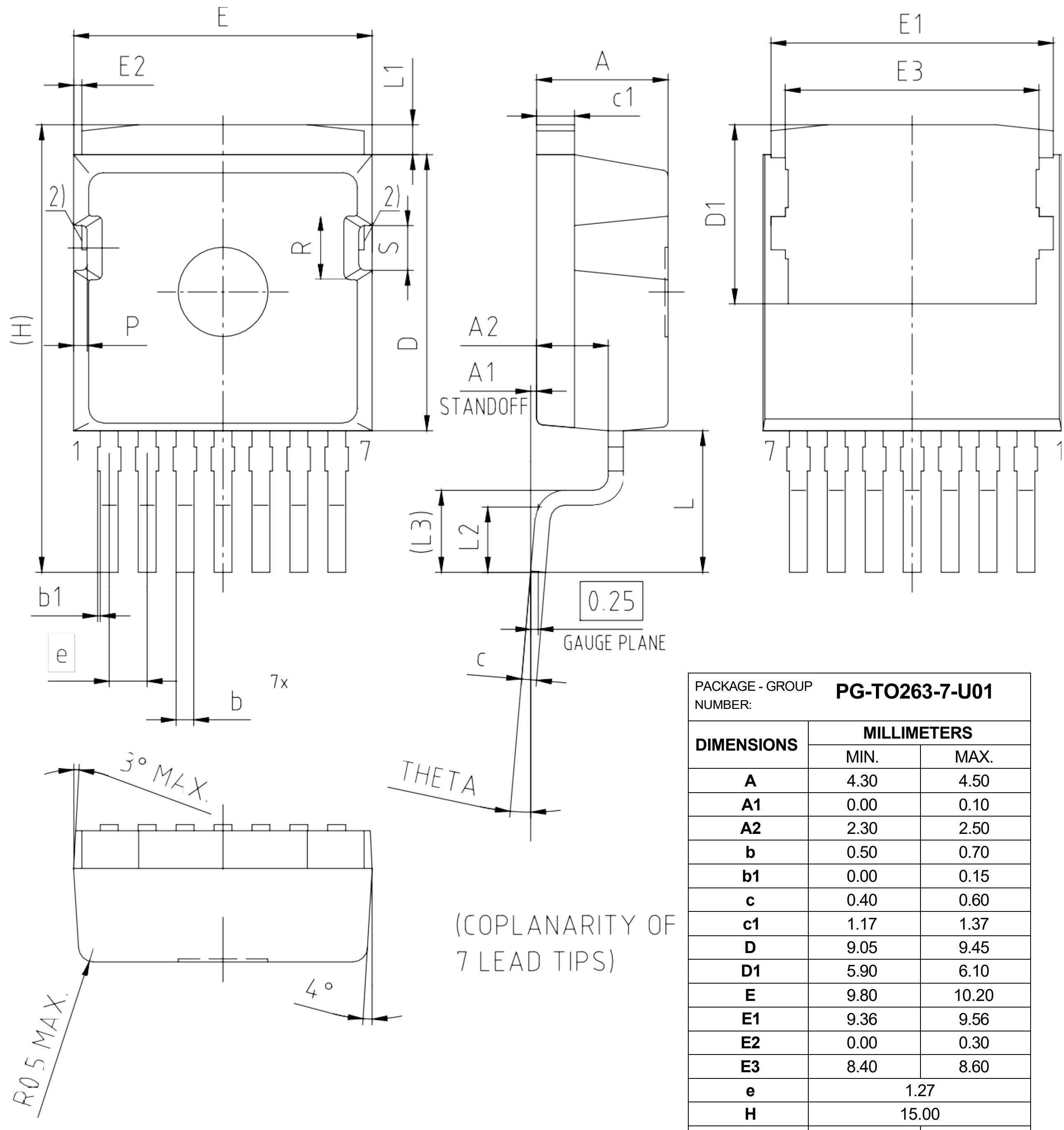
V_{GS} = 0/18 V, I_{SD} = 20.4 A, V_{DD} = 800 V



Typical switching energy as a function of dead time / blanking time, test circuit in Fig. F, 2nd device own body diode: V_{GS} = -5 V $E = f(t_{dead})$ V_{GS} = 0/18 V, I_D = 20.4 A, T_{vj} = 175 °C, $R_{G,ext}$ = 2.3 Ω V_{DD} = 800 V	**Max. transient thermal impedance (MOSFET/diode)** $Z_{th(j-c),max} = f(t_p)$ $D = t_p/T$
	

i	1	2	3	4
r_i[K/W]	0.01644112	0.05819063	0.1463206	0.314938
τ_i[s]	5.4871E-6	9.03455E-5	0.001056756	0.004867395

5 封装外形



PACKAGE - GROUP NUMBER:	PG-TO263-7-U01	
DIMENSIONS	MILLIMETERS	
	MIN.	MAX.
A	4.30	4.50
A1	0.00	0.10
A2	2.30	2.50
b	0.50	0.70
b1	0.00	0.15
c	0.40	0.60
c1	1.17	1.37
D	9.05	9.45
D1	5.90	6.10
E	9.80	10.20
E1	9.36	9.56
E2	0.00	0.30
E3	8.40	8.60
e	1.27	
H	15.00	
L	4.20	5.20
L1	0.70	1.30
L2	1.70	2.30
L3	2.70	
P	0.35	0.55
R	2.03	2.23
S	1.40	1.60
THETA	0.00°	8.00°

NOTES:
1) ALL METAL SURFACES TIN PLATED EXCEPT AREA OF CUT
2) MOLD FILLING IS ACCEPTABLE AT THIS AREA

图 1

6 测试条件

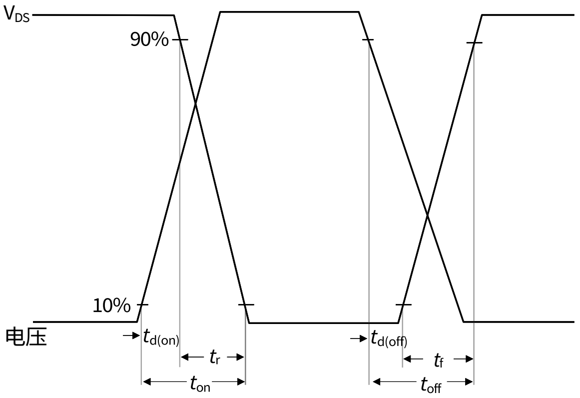
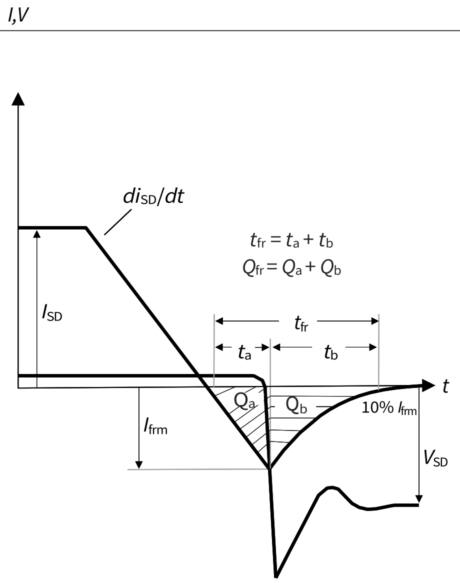


图 A.**开关时间的定义**



图B.**体二极管开关特性的定义**

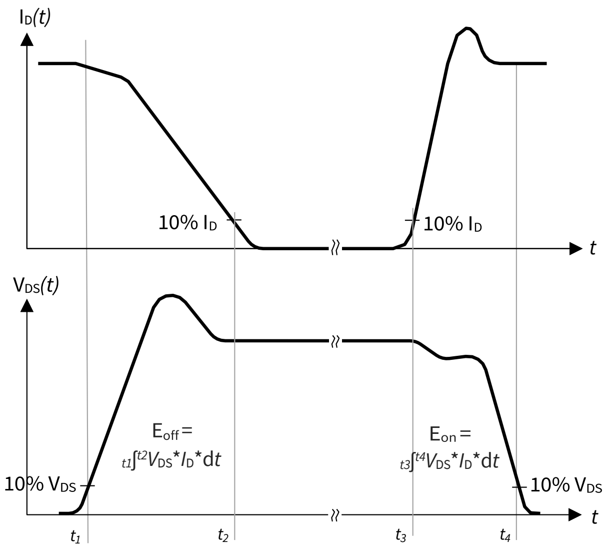


图 C.**开关损耗的定义**

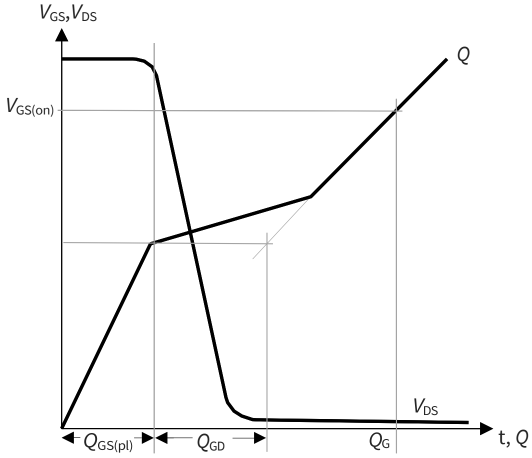


图 D. **QGD 的定义**

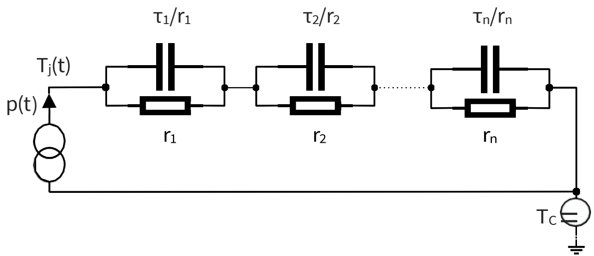
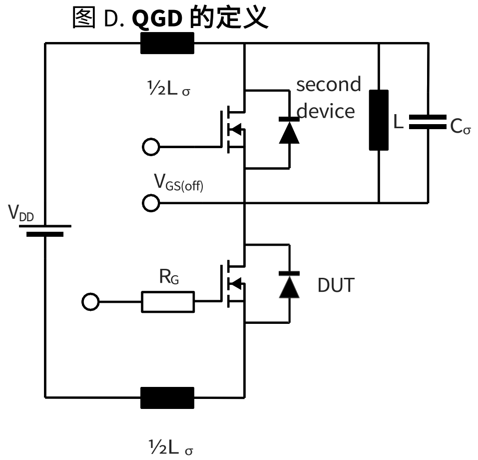


图 E.**热等效电路**



图F.**动态测试电路**寄生电感

Lσ，寄生电容C_σ，

图 2

修订记录

Document revision	Date of release	Description of changes
1.00	2024-07-03	Final datasheet

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Edition 2025-04-17

Published by

Infineon Technologies AG

81726 Munich, Germany

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